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Colleen J. Dew

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 2827

<u>In re application of</u>	:	November 25, 2002
Hormazdyar H. Dalal et al.	:	Examiner: John B. Vigushin
Serial No. : 09/158,616	:	
Filed: September 22, 1998	:	IBM Corporation Dept. 18G/Bldg. 300-482 2070 Route 52 Hopewell Junction, NY 12533-6531
Title: A MULTI-LEVEL ELECTRONIC PACKAGE AND METHOD FOR MAKING SAME	:	

Amendment

**FAX RECEIVED**

Commissioner for Patents and Trademarks  
Washington, D.C. 20231

NOV 25 2002

TECHNOLOGY CENTER 2800

Sir:

Kindly amend the claims as follows:

- 1 1. (4th amendment) A package for containing electronic components, the
- 2 package comprising:
- 3       a first circuitized card;
- 4       a second circuitized card;
- 5       an interposer interposed between the first and second circuitized cards,
- 6       the interposer having an opening, the opening in the interposer and the first and
- 7       second circuitized card forming a cavity for containing at least one electronic
- 8       component wherein the first circuitized card has a bottom surface and there is at
- 9       least one component mounted to the bottom surface, wherein the interposer, first
- 10      circuitized card, and second circuitized card are circuitized multi-layer organic
- 11      laminate cards, wherein the first circuitized card and interposed are electrically
- 12      and physically connected through a ball grid array and the interposer and the